What is claimed is:

1. A package for electrically connecting to an external printed wiring board and an external electronic device comprising:

a substrate electrically connected to the external printed wiring board;

a semiconductor chip disposed on and electrically connected to the substrate; and

a connector disposed on the substrate for electrically connecting the semiconductor chip to the external electronic device.

2. The package as claimed in claim 1, wherein the substrate comprises a plurality of solder balls and is electrically connected to the semiconductor chip for electrically connecting the semiconductor chip to the external printed wiring board.

3. The package as claimed in claim 1, wherein the substrate comprises a plurality of pins and is electrically connected to the semiconductor chip for electrically connecting the semiconductor chip to the external printed wiring board.

4. The package as claimed in claim 1, wherein the connector is disposed on and electrically connected to the substrate by a surface mount technology process.

5. The package as claimed in claim 1, wherein the semiconductor chip is electrically connected to the substrate by a wire bonding process.

6. The package as claimed in claim 1, wherein the semiconductor chip is electrically connected to the substrate by a flip chip technology process.

7. The package as claimed in claim 1, further comprising a molding compound for encapsulating the semiconductor chip.

8. A package for electrically connecting to an external printed wiring board and an external electronic device comprising:

a first substrate;

a first semiconductor chip electrically connected to the first substrate;

a second substrate;

a second semiconductor chip electrically connected to the second substrate;

a medium substrate electrically connected to the first substrate and the second substrate; and

a connector electrically connected to the first substrate and the second substrate,

wherein the first substrate is electrically connected to the external printed wiring board and the connector is electrically connected to the external electronic device.

9. The package as claimed in claim 8, wherein the first substrate comprises a plurality of solder balls for electrically connecting to the external printed wiring board.

10. The package as claimed in claim 8, wherein the first substrate comprises a plurality of pins for electrically connecting to the external printed wiring board.

11. The package as claimed in claim 8, wherein the first semiconductor chip and the second semiconductor chip are electrically connected to the first and the second substrates by a wiring bonding process, respectively.

12. The package as claimed in claim 8, wherein the first and the second semiconductor chips are electrically connected to the first and the second substrates by a flip chip technology process, respectively.

13. The package as claimed in claim 8, further comprising a first molding compound and a second molding compound for encapsulating the first and second semiconductor chips, respectively.